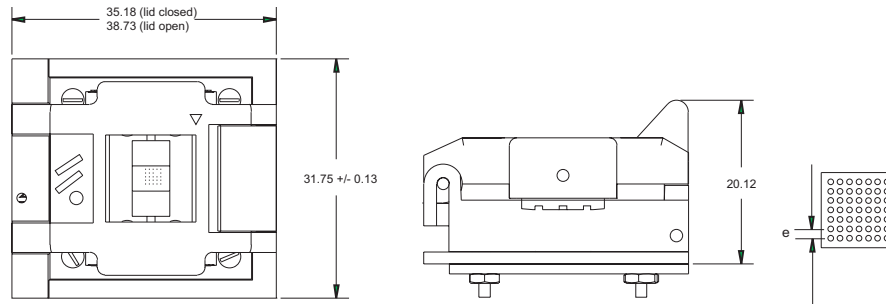


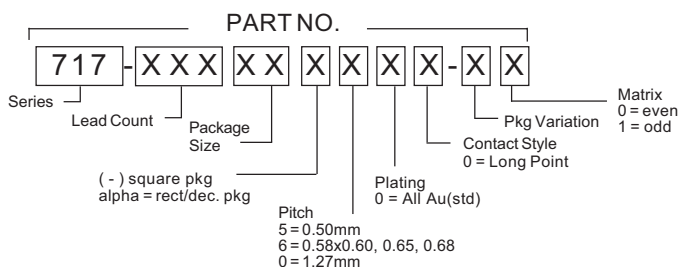
717 Series LGA CSP Socket for Microarray Packages

- Clamshell design, Compression surface mount
- Spring and probe contact
- Pointed probe contacts solder pad
- Pointed probe maintains continuous contact to PCB
- Spring loaded pressure pad and locator plate



Pitch e (mm)	Lead Count	Package Size (mm)	Matrix	Pad Dia. (mm)	Part Number
0.50	15	2.5 X 2.5	4 X 4	0.25-0.35	717-01502A-500-A0
	24	3 X 3	5 X 5	0.25-0.35	717-02403-500-A1
	40	4 X 4	7 X 7	0.25 min.	717-04004-50X-XX
	48	4 X 4	7 X 7	0.25-0.35	717-04804-500-A1
	48	6 X 4	11 X 6	0.24-0.34	717-04806A500-B1
	56	5 X 5	9 X 9	0.25 min.	717-05605-50X-XX
	64	5 X 5	9 X 9	0.20-0.30	717-06405-500-A1
	80	5 X 5	9 X 9	0.25 min.	717-08005-50X-XX
	81	5 X 5	9 X 9	0.25 min.	717-08105-50X-XX
	81	5 X 5	9 X 9	0.25-0.35	717-08105-500-A1
	83	6.22 X 6.22	10 X 10	0.20-0.30	717-08306-500-A0
	96	6 X 6	11 X 11	0.25 min.	717-09606-50X-XX
	112	9 X 9	16 X 16	0.23-0.33	717-11209-500-A0
	120	6 X 6	11 X 11	0.25-0.35	717-12006-500-A1
	120	7 X 7	13 X 13	0.20-0.30	717-12007-500-A1
	143	7 X 7	12 X 12	0.25 min.	717-14307-50X-XX
	144	8 X 8	15 X 15	0.25-0.35	717-14408-500-C1
	148	9 X 9	16 X 16	0.23-0.33	717-14809-500-A0
168	7 X 7	13 X 13	0.25-0.35	717-16807-500-A1	
176	9 X 9	16 X 16	0.23-0.33	717-17609-500-A0	
188	9 X 9	17 X 17	0.25-0.35	717-18809-500-A1	
0.58 X 0.60	22	2.918 X 3.740	4 X 6	0.22-0.28	717-02203A600-A0
0.65	321	15 X 15	21 X 21	0.25-0.35	717-32115-600-A1
0.68	32	5.4 X 3.8	7 X 5	0.22-0.28	717-03205B600-A1
1.27	87	15.5 X 10.5	11 X 8	0.75-0.85	717-08715A000-A1

DESCRIPTION & ORDERING INFORMATION



MATERIALS & SPECIFICATIONS

- Socket Body: PEI, PES or Equivalent
- Contact: Beryllium Copper Alloy
- Contact Plating: Gold over Nickel
- Contact Normal Force: 12-15 grams typical
- Contact Resistance: 350 mΩ typical
- Temperature Rating: Burn-in @125°C
- Durability: 10,000 cycles min.